# MN4021B/MN4021BS

# 8-Bit Static Shift Register

#### ■ Outline

The MN4031B/S consisting of eight register cells which respectively have parallel inputs is an 8-bit static shift register to enable both clock synchronizing series input/series output conversion and parallel input/series output conversion by control of the parallel/series control input (PL).

#### ■ Trush Table Serial operation

		Input		Output				
n	CP	Ds	PL	O <sub>5</sub>	O <sub>6</sub>	O <sub>7</sub>		
1		D <sub>1</sub>	L	<b>X</b> .	×	×		
2	\	$D_2$	L	×	×	×		
3		$D_3$	L	×	×	×		
6	5	×	L	$D_1$	×	×		
7	5	×	L	D <sub>2</sub>	Dı	×		
8		×	L	$D_3$	$D_z$	D <sub>1</sub>		
	7	×	L	no change				

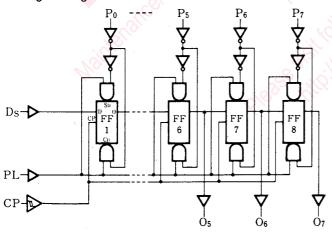
#### Parallel operation

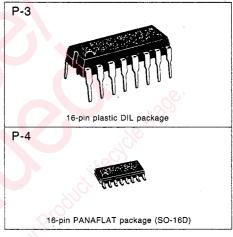
		Input			10 :	
n	CP	Ds	PL	O <sub>s</sub>	0,	O <sub>1</sub>
	×	×	Н	P <sub>5</sub>	P <sub>6</sub>	Ρ,

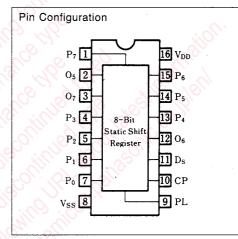
Note) × : don't care Dn: H or L

n : Number of clock pulse

### ■ Logic Diagram







■ Absolute Maximum Ratings (Ta=25°C)

Item		Symbol	Rating	Unit
Supply voltage		$V_{\mathrm{DD}}$	-0.5~+18	V
Input voltage		$V_1$	-0.5~V <sub>DD</sub> +0.5*	V
Output pin voltage		V <sub>O</sub> .	-0.5~V <sub>DD</sub> +0.5*	V
Peak input · output pin current		$\pm I_{\mathfrak{l}}$	max. 10	mA
Power dissipation $Ta = -40 \sim +60 ^{\circ}C$		D	max. 400	mW
(per package)	$Ta = +60 \sim +80^{\circ}C$	$P_D$	Decrease to 200mW at the rate of 8mW/°C	11144
Power dissipation (per output pin)		Po	max. 100	mW
Operating ambient temperature		$T_{opr}$	-40~+85	°C
Storage temperature		$T_{ m stg}$	-65~+150	°C

<sup>\*</sup> V<sub>DD</sub>+0.5V should be lower than 18V.

### ■ DC Characteristics (V<sub>SS</sub>=0V)

DC Characteristics	( <b>v</b> ss:	= U V )							70.		
Item	$V_{\mathrm{DD}}$	V <sub>DD</sub> Symbol Condition		$Ta = -40^{\circ}C$		°C Ta=25°C		Ta=85°C		Unit	
item	(V)	Symbol	Condition		min.	max.	min.	max.	min.	max.	Oint
	5					20		20		150	
Static supply current	10	$I_{\mathrm{DD}}$	$V_i = V_{\rm SS}$ or	$V_{DD}$		40	77/	40	_	300	μΑ
	15					80	<u></u>	80	_	600	
	5		$V_I = V_{SS}$ or	V		0.05	_	0.05		0.05	
Output voltage low level	10	V <sub>ot.</sub>	$ I_0  < 1\mu A$	עט •	-0	0.05	_	0.05	_	0.05	V
	15		1101~1μΑ		4	0.05		0.05		0.05	
	5		$V_1 = V_{SS}$ or $V_{DD}$		4.95	>.—	4.95	_	4.95	_	
Output voltage high level	10	V <sub>OH</sub>	$ I_0  < 1\mu A$	V DD	9.95	<u>-</u>	9.95	_	9.95	<del>-</del> .	V
	15		1101/1µA		14.95		14.95		14.95		)
	5			$V_0 = 0.5V$ or 4.5V	) — (	1.5	00	1.5		1.5	
Input voltage low level	10	$V_{iL}$	$ I_0  < 1\mu A$	$V_0=1V$ or $9V$	4	-3	<u> </u>	3	40)	3	V
	15			$V_0 = 1.5V$ or $13.5V$	∑ <u> </u>	4		4	7	4	
	5		2	$V_0 = 0.5V$ or $4.5V$	3.5	<u> </u>	3.5	1 <del>0</del> 5	3.5	6	
Input voltage high level	10	$V_{IH}$	$ I_0  < 1\mu A$	$V_0=1V$ or $9V$	7	-	7	2	7		V
	15		9,	$V_0 = 1.5V$ or $13.5V$	11	<i>-</i>	11		11	_	
	5		$V_0 = 0.4V$ ,	$V_i=0$ or $5V$	0.52	<u> </u>	0.44	( <del>(</del>	0.36	_	
Output current low level	10	IoL	$V_0 = 0.5V$ ,	$V_0 = 0.5V$ , $V_1 = 0$ or $10V$		_0	1.1	32	0.9		mA
	15	60),	$V_0 = 1.5V$ , $V_1 = 0$ or $15V$		3.6	22	3		2.4		
	5	5	$V_0$ =4.6V, $V_I$ =0 or 5V $V_0$ =9.5V, $V_I$ =0 or 10V $V_0$ =13.5V, $V_I$ =0 or 15V		0.52	-(	0.44		0.36		
Output current high level	10	$-I_{OH}$			1.3	· <del>(</del>	1.1	_	0.9	_	mA
<u> </u>	15				3.6		3		2.4		
Output current high level	5	-I <sub>OH</sub>	$V_0 = 2.5V$ ,	V <sub>i</sub> =0 or 5V	1.7		1.4		1.1	_	mA
Input leakage current	15	$\pm I_{l}$	$V_1=0$ or 15	<i>N</i> :	0.3	-	0.3	_	1	μA	

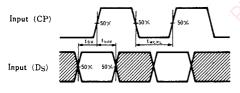
## ■ Switching Characteristics (Ta=25°C, V<sub>ss</sub>=0V, C<sub>L</sub>=50pF)

Item	V <sub>DD</sub> (V)	Symbol	min.	typ.	max.	Unit
	5		_	60	180	
Output rise time	10	t <sub>TLH</sub>		30	90	ns
	15		_	20	60	
	5		_	60	180	
Output fall time	10	t <sub>THL</sub>		30	90	ns
	15		_	20	60	

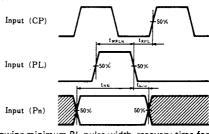
#### ■ Switching Characteristics (cont.)

Item	V <sub>DD</sub> (V)	Symbol	min.	typ.	max.	Unit
Propagation time	5		— — — — — — — — — — — — — — — — — — —	170	510	
CP→On (H→L)	10	t <sub>PHL</sub>	_	65	195	ns
	15		_	45	135	
Propagation time	5		_	130	390	
CP→On (L→H)	10	t <sub>PLH</sub>	_	55	165	ns
Cr→On (L→H)	15			40	120	
Decongration time	5			240	720	
Propagation time	10	t <sub>PHL</sub>		90	270	ns
$PL \rightarrow On (H \rightarrow L)$	15			60	180	
<b>D</b>	5			175	525	16.
Propagation time	10	t <sub>PLH</sub>		70	210	ns
PL→On (L→H)	15	1	(	50	150	
0	5			45	135	
Set-up time	10	t <sub>su</sub>	_	15	45	ns
$D_s \rightarrow CP$	15		_	10	30	
_	5			70	210	
Set-up time	10	t <sub>su</sub>		25	75	ns
Pn→PL	15	-su	_	20	60	
	5			20	60	
Hold time	10	thold	_ so)	10	30	ns
$D_S \rightarrow CP$	15	Choid	_0	8	24	113
	5		1100	-10	24	10)
Hold time	10	thold	10/12 CS	0	24	ns
Pn→PL	15	- rioid		0 0	24	113
	5	(3)		55	165	
Minimum clock pulse width	10	twcpl		20	60	ns
Minimum clock pulse width	15	LWCPL		15	45	118
	5		10 TO	75	225	
Minimum PL pulse width	10	1000	0, -0,	25		
Minimum FL puise widur	15	twplh	, 4 <u>12</u> , 4	20	75 60	ns
		5	9-4			
DI	5		30.50	65	195	
PL recovery time	10	t <sub>RPL</sub>	6 T	20	60	ns
	15	7	- 10	15	45	
26	5		4	9	_	
Maximum clock frequency	10	$f_{max}$	12	25		MHz
	15		. 18	37		
Input capacitance		C <sub>I</sub>	D. 14/2	-	7.5	pF

#### Switching waveforms



Waveforms showing minimum clock pulse width, set-up time and hold time for CP and  $\mathsf{D}_{\mathsf{S}}$ .



Waveforms showing minimum PL pulse width, recovery time for PL, and set-up and hold times for  $P_{n}\,$  to PL. Set-up and hold times are shown as positive values but may be specified as negative values.

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